

# General Purpose Transistor PNP Silicon MMBT3906L, SMMBT3906L

## **Features**

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	$V_{CEO}$	-40	Vdc
Collector - Base Voltage	V <sub>CBO</sub>	-40	Vdc
Emitter - Base Voltage	V <sub>EBO</sub>	-5.0	Vdc
Collector Current - Continuous	Ic	-200	mAdc
Collector Current - Peak (Note 3)	I <sub>CM</sub>	-800	mAdc

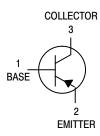
#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina =  $0.4 \times 0.3 \times 0.024$  in. 99.5% alumina.
- 3. Reference SOA curve.





### MARKING DIAGRAM



2A = Specific Device Code

M = Date Code\*

■ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

### **ORDERING INFORMATION**

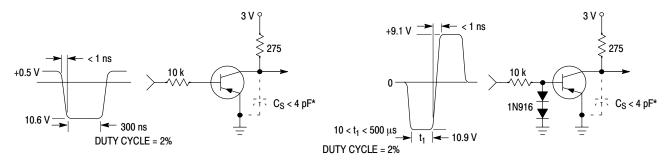
Device	Package	Shipping <sup>†</sup>
MMBT3906LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBT3906LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
SMMBT3906LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SMMBT3906LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Charac	teristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS		4	•		
Collector – Emitter Breakdown Voltage $(I_C = -1.0 \text{ mAdc}, I_B = 0)$			-40	_	Vdc
Collector – Base Breakdown Voltage $(I_C = -10 \mu Adc, I_E = 0)$			-40	_	Vdc
Emitter – Base Breakdown Voltage $(I_C = -10 \mu Adc, I_C = 0)$		V <sub>(BR)EBO</sub>	-5.0	_	Vdc
Base Cutoff Current (V <sub>CE</sub> = -30 Vdc, V <sub>EB</sub> = -3.0 Vdc)		I <sub>BL</sub>	-	-50	nAdc
Collector Cutoff Current (V <sub>CE</sub> = -30 Vdc, V <sub>EB</sub> = -3.0 Vdc)		I <sub>CEX</sub>	-	-50	nAdc
ON CHARACTERISTICS (Note 4)					
DC Current Gain		H <sub>FE</sub>	60 80 100 60 30	- 300 - -	-
Collector – Emitter Saturation Voltage $ \begin{pmatrix} I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc} \\ I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc} \end{pmatrix} $			- -	-0.25 -0.4	Vdc
Base – Emitter Saturation Voltage $ \begin{array}{l} (I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc}) \\ (I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc}) \end{array} $		V <sub>BE(sat)</sub>	-0.65 -	-0.85 -0.95	Vdc
SMALL-SIGNAL CHARACTERISTICS		1		•	
Current – Gain – Bandwidth Product (I <sub>C</sub> = –10 mAdc, V <sub>CE</sub> = –20 Vdc, f	= 100 MHz)	f <sub>T</sub>	250	_	MHz
Output Capacitance (V <sub>CB</sub> = -5.0 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)		C <sub>obo</sub>	-	4.5	pF
Input Capacitance ( $V_{EB} = -0.5 \text{ Vdc}$ , $I_C = 0$ , $f = 1.0 \text{ M}$	Hz)	C <sub>ibo</sub>	-	10	pF
Input Impedance ( $I_C = -1.0 \text{ mAdc}$ , $V_{CE} = -10 \text{ Vdc}$ , $f = 1.0 \text{ kHz}$ )		h <sub>ie</sub>	2.0	12	kΩ
Voltage Feedback Ratio ( $I_C = -1.0 \text{ mAdc}$ , $V_{CE} = -10 \text{ Vdc}$ , $f = 1.0 \text{ kHz}$ )		h <sub>re</sub>	0.1	10	X 10 <sup>-4</sup>
Small – Signal Current Gain ( $I_C = -1.0 \text{ mAdc}$ , $V_{CE} = -10 \text{ Vdc}$ , $f = 1.0 \text{ kHz}$ )		h <sub>fe</sub>	100	400	-
Output Admittance ( $I_C = -1.0 \text{ mAdc}$ , $V_{CE} = -10 \text{ Vdc}$ , $f = 1.0 \text{ kHz}$ )		h <sub>oe</sub>	3.0	60	μmhos
Noise Figure (I <sub>C</sub> = -100 $\mu$ Adc, V <sub>CE</sub> = -5.0 Vdc, R <sub>S</sub> = 1.0 k $\Omega$ , f = 1.0 kHz)		NF	-	4.0	dB
SWITCHING CHARACTERISTICS		•	•	•	
Delay Time	$(V_{CC} = -3.0 \text{ Vdc}, V_{BE} = 0.5 \text{ Vdc},$	t <sub>d</sub>	-	35	ne
Rise Time	I <sub>C</sub> = -10 mAdc, I <sub>B1</sub> = -1.0 mAdc)	t <sub>r</sub>	-	35	ns
Storage Time	$(V_{CC} = -3.0 \text{ Vdc}, I_{C} = -10 \text{ mAdc},$	t <sub>s</sub>	-	225	ns
Fall Time	$I_{B1} = I_{B2} = -1.0 \text{ mAdc}$	t <sub>f</sub>	-	75	1.0

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.



\* Total shunt capacitance of test jig and connectors

Figure 1. Delay and Rise Time Equivalent Test Circuit

Figure 2. Storage and Fall Time Equivalent Test Circuit

## TYPICAL TRANSIENT CHARACTERISTICS

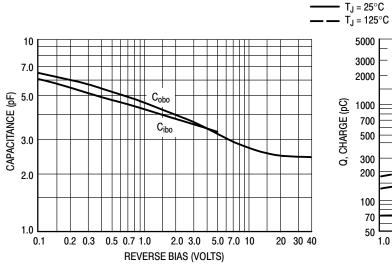


Figure 3. Capacitance

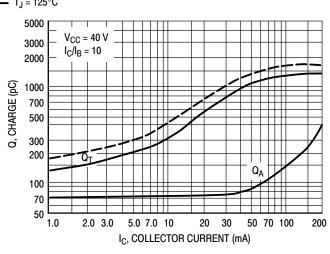


Figure 4. Charge Data

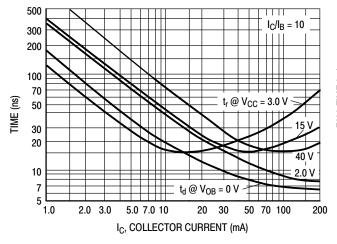


Figure 5. Turn - On Time

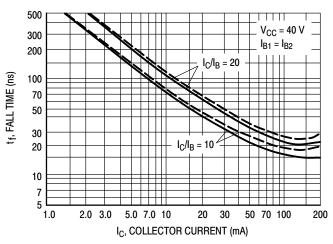
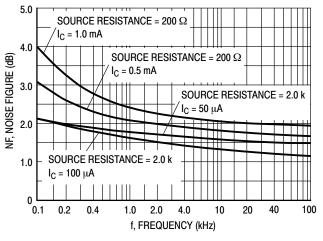


Figure 6. Fall Time

# TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth = 1.0 \text{ Hz})$ 



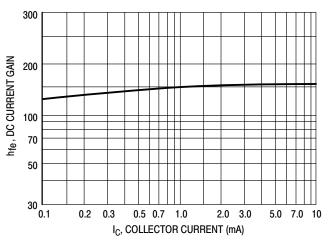
f = 1.0 kHz10 NF, NOISE FIGURE (dB) 8 6 4  $I_{C} = 50 \, \mu A$  $I_C = 100 \mu A$ 0.2 40 100 0.4 0.1 1.0 2.0 4.0 R<sub>0</sub>, SOURCE RESISTANCE (k OHMS)

Figure 7.

Figure 8.

## **h PARAMETERS**

 $(V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C})$ 



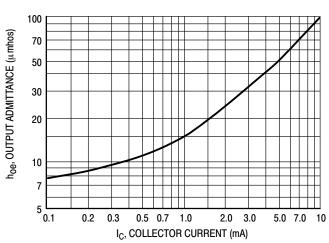
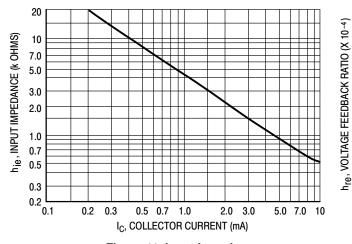


Figure 9. Current Gain

Figure 10. Output Admittance



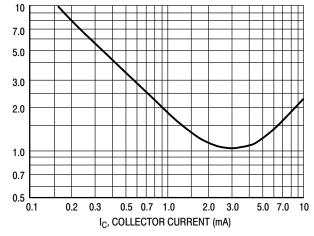


Figure 11. Input Impedance

Figure 12. Voltage Feedback Ratio

## TYPICAL STATIC CHARACTERISTICS

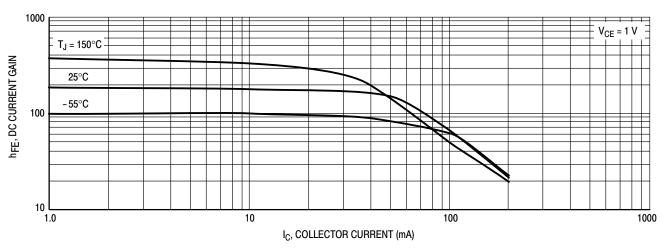


Figure 13. DC Current Gain

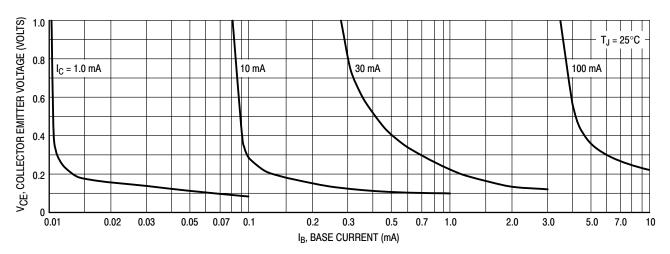


Figure 14. Collector Saturation Region

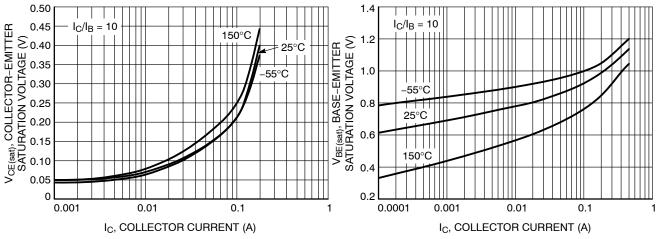


Figure 15. Collector Emitter Saturation Voltage vs. Collector Current

Figure 16. Base Emitter Saturation Voltage vs. **Collector Current** 

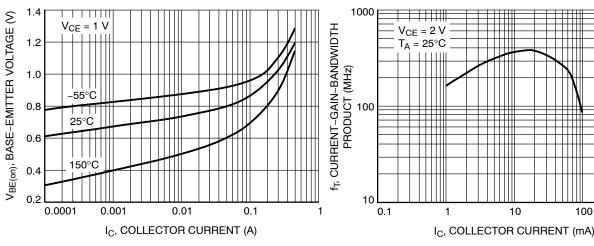


Figure 17. Base Emitter Voltage vs. Collector Current

Figure 18. Current Gain Bandwidth vs. **Collector Current** 

100

1000

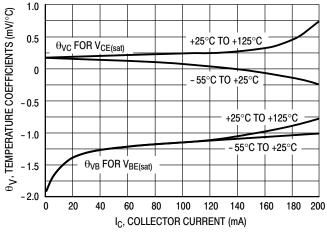


Figure 19. Temperature Coefficients

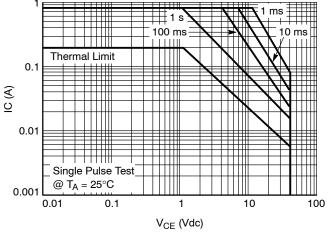


Figure 20. Safe Operating Area

**MILLIMETERS** 

MIN

0.89

0.01

0.37

0.08

2.80

1.20

1.78

0.30

0.35

2.10

O°

NOM

1.00

0.06

0.44

0.14

2.90

1.30

1.90

0.43

0.54

2.40

\_\_\_





## SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

**DATE 14 AUG 2024** 

MAX

1.11

0.10

0.50

0.20

3.04

1.40

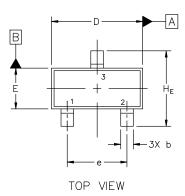
2.04

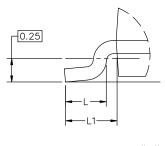
0.55

0.69

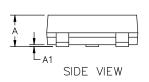
2.64

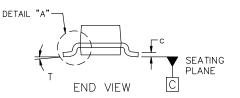
10°





DETAIL "A" Scale 3:1





# 2.90 3X 0.95 3X 0.56 -0.95 PITCH

### NOTES:

DIM

Α

Α1

b

С

D

Ε

е L

L1

HE

Τ

- DIMENSIONING AND TOLERANCING 1. PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS:
- MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

## **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code

= Pb-Free Package



\* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **STYLES ON PAGE 2**

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<sup>\*</sup>This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

## SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR		NODE D CONNECTION ATHODE	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11:         STYLE 12:           PIN 1. ANODE         PIN 1. CA           2. CATHODE         2. CA           3. CATHODE-ANODE         3. AN	ATHODE PIN 1. SOURCE ATHODE 2. DRAIN	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE			STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23:         STYLE 24:           PIN 1. ANODE         PIN 1. GAT           2. ANODE         2. DR/           3. CATHODE         3. SOU	TE PIN 1. ANODE AIN 2. CATHODE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE			

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